

## PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1  
 Stylesheet Version v1.2

EPAS ID: PAT5002281

|   |  |
|---|--|
| <b>SUBMISSION TYPE:</b>   | NEW ASSIGNMENT                                   |
| <b>NATURE OF CONVEYANCE:</b>  | ASSIGNMENT                                       |
| <b>CONVEYING PARTY DATA</b>   |  |
| <b>Name</b>   | <b>Execution Date</b>                            |
| CHIA-JUNG HSU   | 08/25/2014                                       |
| NENG-KUO CHEN   | 08/25/2014                                       |
| TENG-CHUN TSAI  | 08/25/2014                                       |
| <b>RECEIVING PARTY DATA</b>   |  |
| <b>Name:</b>  | TAIWAN SEMICONDUCTOR MANUFACTURING COMPANY, LTD. |
| <b>Street Address:</b>  | NO. 8, LI-HSIN RD. 6                             |
| <b>Internal Address:</b>  | SCIENCE-BASED INDUSTRIAL PARK                    |
| <b>City:</b>  | HSIN-CHU   |
| <b>State/Country:</b>   | TAIWAN   |
| <b>Postal Code:</b>   | 300-77   |
| <b>PROPERTY NUMBERS Total: 1</b>  |  |
| <b>Property Type</b>  | <b>Number</b>                                    |
| <b>Application Number:</b>  | 16004763   |
| <b>CORRESPONDENCE DATA</b>  |  |
| <b>Fax Number:</b>  | (214)200-0853                                    |
| <i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i> |  |
| <b>Phone:</b>   | 214-651-5000                                     |
| <b>Email:</b>   | ipdocketing@haynesboone.com                      |
| <b>Correspondent Name:</b>  | HAYNES AND BOONE, LLP IP SECTION                 |
| <b>Address Line 1:</b>  | 2323 VICTORY AVENUE                              |
| <b>Address Line 2:</b>  | SUITE 700  |
| <b>Address Line 4:</b>  | DALLAS, TEXAS 75219                              |
| <b>ATTORNEY DOCKET NUMBER:</b>  | 20140421/24061.2882US03                          |
| <b>NAME OF SUBMITTER:</b>   | JANIE MARTINEZ-HOLM                              |
| <b>SIGNATURE:</b>   | /JANIE MARTINEZ-HOLM/                            |
| <b>DATE SIGNED:</b>   | 06/12/2018                                       |
| <b>Total Attachments: 2</b>   |  |
| source=24061-2882US03_TSMC_Assignment_Parent#page1.tif  |  |
| source=24061-2882US03_TSMC_Assignment_Parent#page2.tif  |  |

Docket No.: 2014-0421 / 24061.2882  
Customer No.: 42717

## ASSIGNMENT

WHEREAS, we,

- |     |                |    |   |
|-----|----------------|----|---|
| (1) | Chia-Jung Hsu  | of | No.5, 1st Neighborhood, Dongping Road<br>Cailliao Village Dacheng Township,<br>Changhua County 52747, Taiwan R.O.C. |
| (2) | Neng-Kuo Chen  | of | 11F., No. 329, Section 2, Gongdao 5th Road<br>East District, Hsinchu City 300, Taiwan R.O.C.                        |
| (3) | Teng-Chun Tsai | of | 11 F No. 188, Guanxin West Street<br>East District, Hsinchu City, Taiwan R.O.C.                                     |

have invented certain improvements in

### SLURRY COMPOSITION FOR CHEMICAL MECHANICAL POLISHING OF GE-BASED MATERIALS AND DEVICES

for which we have executed an application for Letters Patent of the United States of America,

  X   of even date filed herewith; and  
           filed on                                  and assigned application number                                 ; and

WHEREAS, we authorize the attorney of record to update this document to include Patent Office information as deemed necessary (i.e., filing date, serial number, etc.);

WHEREAS, Taiwan Semiconductor Manufacturing Company, Ltd., ("TSMC"), No. 8, Li-Hsin Rd. 6, Science-Based Industrial Park Hsin-Chu, Taiwan 300-77, Republic of China. is desirous of obtaining the entire right, title, and interest in, to and under the said invention and the said application in the United States of America and in any and all countries foreign thereto;

NOW, THEREFORE, for good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, and other good and valuable consideration, we have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto the said TSMC, its successors, legal representatives, and assigns, the entire right, title, and interest in, to and under the said invention, and the said application, and all divisional, renewal, substitutional, and continuing applications thereof, and all Letters Patent of the United States of America which may be granted thereon and all reissues and extensions thereof, and all applications for Letters Patent which may be filed for said invention in any country or countries foreign to the United States of America, and all extensions, renewals, and reissues thereof, and all prior patents and patent applications from which a filing priority of the above-described patent application may be obtained, including the right to collect past damages; and we hereby authorize and request the Commissioner of Patents of the United States of America, and any official of any country or countries foreign to the United States of America, whose duty it is to issue patents on applications as aforesaid, to issue all Letters Patent for said invention to the said TSMC, its successors, legal representatives and assigns, in accordance with the terms of this instrument.

AND WE HEREBY covenant that we have full right to convey the entire interest herein assigned, and that we have not executed, and will not execute, any agreement in conflict herewith.

Docket No.: 2014-0421 / 24061.2882  
Customer No.: 42717

AND WE HEREBY further covenant and agree that we will communicate to said TSMC, its successors, legal representatives and assigns, any facts known to us respecting said invention, and testify in any legal proceedings, sign all lawful papers, execute all divisional, renewal, substitutional, continuing, and reissue applications, make all rightful declarations and/or oaths and generally do everything possible to aid the said TSMC, its successors, legal representatives and assigns, to obtain and enforce proper patent protection for said invention in all countries.

Inventor Name: Chia-Jung Hsu

Residence Address: No.5, 1st Neighborhood, Dongping Road  
Cailiao Village Dacheng Township,  
Changhua County 52747, Taiwan R.O.C.

Dated: 2014/08/25

*Chia-Jung Hsu*  
Inventor Signature

Inventor Name: Neng-Kuo Chen

Residence Address: 11F., No. 329, Section 2, Gongdao 5th Road  
East District, Hsinchu City 300, Taiwan R.O.C.

Dated: 2014/08/25

*Neng-Kuo Chen*  
Inventor Signature

Inventor Name: Teng-Chun Tsai

Residence Address: 11 F No. 188, Guanxin West Street  
East District, Hsinchu City, Taiwan R.O.C.

Dated: 2014/08/25

*Teng-Chun Tsai*  
Inventor Signature